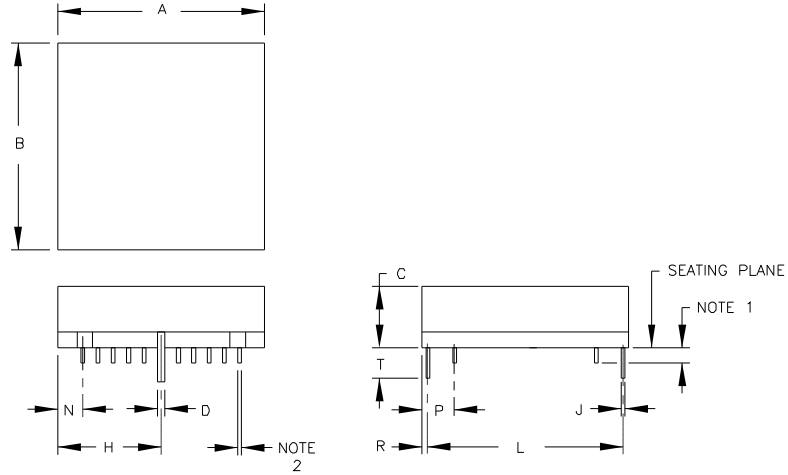


Package Number 124 - EMI Shield



DIM	INCHES		MILLIMETERS		N O T E	DIM	INCHES		MILLIMETERS		N O T E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	1.320	1.380	33.53	35.05							
B	1.320	1.380	33.53	35.05							
C	.350	.450	8.89	11.43							
D	.040	.060	1.02	1.52							
H	.600	.700	15.24	17.78							
J	.015	.025	0.38	0.64							
L	1.180	1.280	29.97	32.51							
N	.150	.250	3.81	6.35							
P	.150	.250	3.81	6.35							
R	.015	.055	0.38	1.40							
T	.130	.230	3.30	5.84							

NOTES:
 1. ENCLOSED MODULE LEAD LENGTH MINUS .050" TO .100" (1.27mm TO 2.54mm).
 2. PIN DIAMETER DETERMINED BY ENCLOSED MODULE.

PACKAGE NUMBER: ZZ124 REV.: A
 JEDEC NUMBER: NONE



PACKAGE DRAWING

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